

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.56	100.0	1.9
<b>Subtotal</b>				<b>0.56</b>	<b>100</b>	<b>1.9</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04	100.0	0.15
<b>Subtotal</b>				<b>0.04</b>	<b>100</b>	<b>0.15</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	3.53	100.0	12
<b>Subtotal</b>				<b>3.53</b>	<b>100</b>	<b>12</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.05
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02	0.03	0.05
	Copper alloy	Iron (Fe)	7439-89-6	0.05	0.1	0.17
	Copper alloy	Copper (Cu)	7440-50-8	51.17	99.84	173.92
<b>Subtotal</b>				<b>51.26</b>	<b>100</b>	<b>174.19</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.64	6.0	8.96
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.07	7.0	10.45
	Filler	Silica fused	60676-86-0	37.78	86.0	128.4
	Carbon Black	Carbon black	1333-86-4	0.44	1.0	1.49
<b>Subtotal</b>				<b>43.93</b>	<b>100</b>	<b>149.3</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01	2.0	0.04
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.05
	Lead alloy	Lead (Pb)	7439-92-1	0.51	95.5	1.74
<b>Subtotal</b>				<b>0.53</b>	<b>100</b>	<b>1.83</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.15	100.0	0.5
<b>Subtotal</b>				<b>0.15</b>	<b>100</b>	<b>0.5</b>
<b>Total</b>				<b>100</b>	<b>100</b>	<b>339.87</b>

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